

# TPC8049-VB Datasheet N-Channel 60-V (D-S) MOSFET

PRODUCT SUMMARY						
V <sub>DS</sub> (V)	R <sub>DS(on)</sub> (Ω)	I <sub>D</sub> (A) <sup>d</sup>	Q <sub>g</sub> (Typ.)			
60	0.012 at V <sub>GS</sub> = 10 V	2 at V <sub>GS</sub> = 10 V 12				
00	0.015 at V <sub>GS</sub> = 4.5 V	11	10.5 nC			



- Halogen-free According to IEC 61249-2-21
   Definition
- Trench Power MOSFET
- Optimized for "Low Side" Synchronous Rectifier Operation



FREE

Available

• 100 %  $\rm R_g$  and UIS Tested

## APPLICATIONS

CCFL Inverter

SO-8		D <b>P</b>
S 1 S 2 S 3 G 4	8 D 7 D 6 D 5 D	G Q F
Top View		N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS T Parameter	Symbol	Limit			
Drain-Source Voltage	V <sub>DS</sub>	60	V		
Gate-Source Voltage		V <sub>GS</sub>	± 20	v	
	T <sub>C</sub> = 25 °C		12 <sup>a</sup>		
Continuous Drain Current ( $T_{1}$ = 150 °C)	T <sub>C</sub> = 70 °C		11		
Continuous Drain Current $(1) = 150^{\circ} C$	T <sub>A</sub> = 25 °C	I <sub>D</sub>	8.0 <sup>b, c</sup>		
	T <sub>A</sub> = 70 °C		7.6 <sup>b, c</sup>		
Pulsed Drain Current	I <sub>DM</sub>	25	Α		
	T <sub>C</sub> = 25 °C	1	4.2		
Continuous Source-Drain Diode Current	T <sub>A</sub> = 25 °C	I <sub>S</sub>	2.1 <sup>b, c</sup>		
Avalanche Current		I <sub>AS</sub>	15		
Single-Pulse Avalanche Energy	L = 0.1 mH	E <sub>AS</sub>	11.2	mJ	
	T <sub>C</sub> = 25 °C		5		
Maximum Power Dissipation	T <sub>C</sub> = 70 °C		3.2	w	
	T <sub>A</sub> = 25 °C	– P <sub>D</sub> –	2.5 <sup>b, c</sup>	vv	
	T <sub>A</sub> = 70 °C	1	1.6 <sup>b, c</sup>		
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient <sup>b, d</sup>	t ≤ 10 s	R <sub>thJA</sub>	38	50	°C/W	
Maximum Junction-to-Foot (Drain)	Steady State	R <sub>thJF</sub>	20	25	C/VV	

Notes:

a. Package limited.

b. Surface mounted on 1" x 1" FR4 board.

c. t = 10 s.

d. Maximum under Steady State conditions is 85 °C/W.



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 V, I_{D} = 250 \mu A$	60			V	
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	1 250 1		55		mV/°C	
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I <sub>D</sub> = 250 μA		- 6.3			
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 250 \ \mu A$	1.0		3.0	V	
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA	
Zana Oata Maltana Daria Orana d	1	V <sub>DS</sub> = 60 V, V <sub>GS</sub> = 0 V			1	μA	
Zero Gate Voltage Drain Current	IDSS	$V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 \text{ °C}$			10		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge 5 \text{ V}, \text{ V}_{GS} = 10 \text{ V}$	25			А	
		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 4.6 A		0.012		-	
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 4.2 A	0.015			Ω	
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 4.6 A		20		S	
Dynamic <sup>b</sup>	•						
Input Capacitance	C <sub>iss</sub>			1100		pF	
Output Capacitance	C <sub>oss</sub>	$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}, \text{ f} = 1 \text{ MHz}$		90			
Reverse Transfer Capacitance	C <sub>rss</sub>			55			
Total Gate Charge	Qg	$V_{DS} = 30 \text{ V}, \text{ V}_{GS} = 10 \text{ V}, \text{ I}_{D} = 4.6 \text{ A}$		21	32		
				10.5	16	nC	
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS} = 30$ V, $V_{GS} = 4.5$ V, $I_{D} = 4.6$ A		3.5			
Gate-Drain Charge	Q <sub>gd</sub>			4.2			
Gate Resistance	R <sub>g</sub>	f = 1 MHz		3.3	5	Ω	
Turn-On Delay Time	t <sub>d(on)</sub>			20	30		
Rise Time	t <sub>r</sub>	$V_{DD}$ = 30 V, $R_L$ = 5.4 $\Omega$		150	225	-	
Turn-Off DelayTime	t <sub>d(off)</sub>	${ m I_D}\cong 5.6~{ m A},~{ m V_{GEN}}$ = 4.5 V, ${ m R_g}$ = 1 $\Omega$		20	30		
Fall Time	t <sub>f</sub>			60	90		
Turn-On Delay Time	t <sub>d(on)</sub>			10	15	ns	
Rise Time	t <sub>r</sub>	$V_{DD}$ = 30 V, $R_{L}$ = 5.4 $\Omega$		15	25	-	
Turn-Off DelayTime	t <sub>d(off)</sub>	$I_D \cong 5.6 \text{ A}, \text{ V}_{\text{GEN}}$ = 10 V, $R_g$ = 1 $\Omega$		25	40		
Fall Time	t <sub>f</sub>			10	15		
Drain-Source Body Diode Characterist	ics						
Continous Source-Drain Diode Current	۱ <sub>s</sub>	T <sub>C</sub> = 25 °C			4.2	•	
Pulse Diode Forward Currenta	I <sub>SM</sub>				25	A	
Body Diode Voltage	V <sub>SD</sub>	I <sub>S</sub> = 2 A		0.8	1.2	V	
Body Diode Reverse Recovery Time	t <sub>rr</sub>	-		25	50	ns	
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>			25	50	nC	
Reverse Recovery Fall Time	t <sub>a</sub>	I <sub>F</sub> = 5.5 A, dl/dt = 100 A/μs, T <sub>J</sub> = 25 °C		19			
Reverse Recovery Rise Time	t <sub>b</sub>			6	1	ns	

Notes:

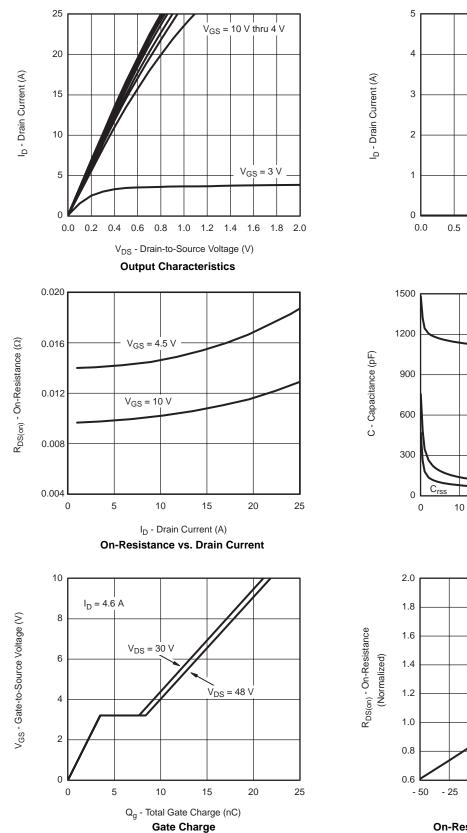
a. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %.

b. Guaranteed by design, not subject to production testing.

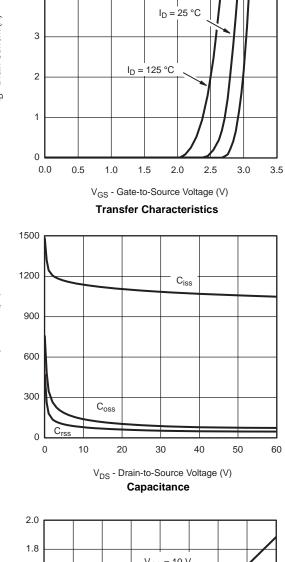
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

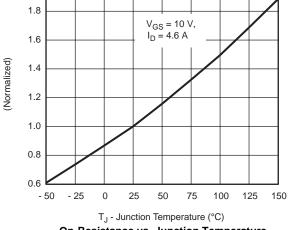


 $T_{\rm C} = -55$ 



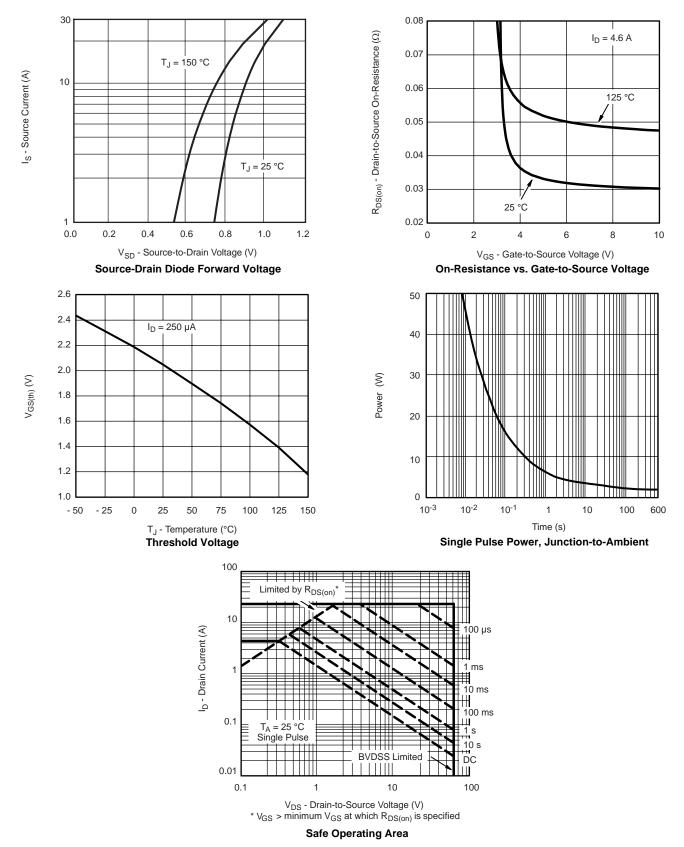
### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted





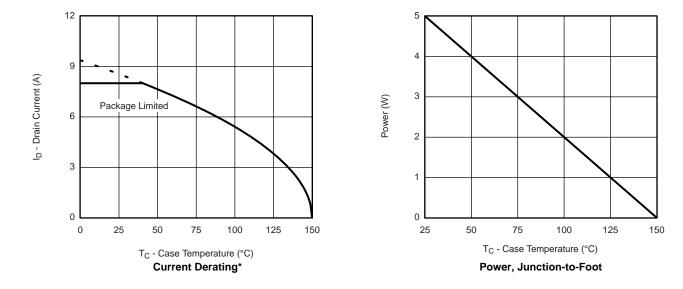
**On-Resistance vs. Junction Temperature** 





### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

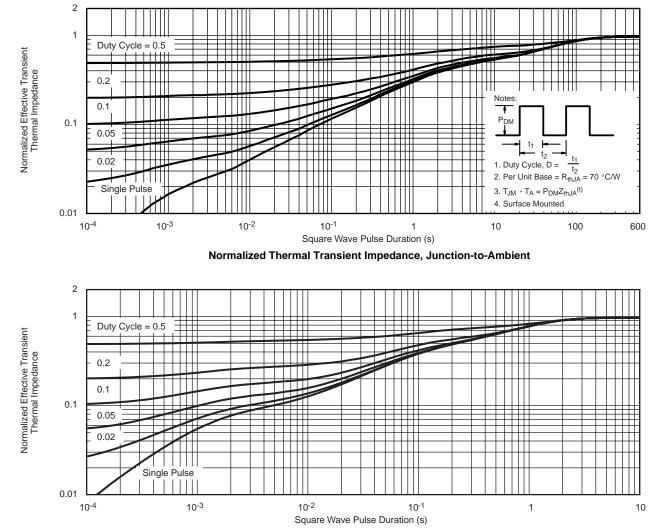




## TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

\* The power dissipation  $P_D$  is based on  $T_{J(max)}$  = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.





### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

Normalized Thermal Transient Impedance, Junction-to-Foot



# SOIC (NARROW): 8-LEAD

JEDEC Part Number: MS-012





	MILLIM	IETERS	INCHES		
DIM	Min	Мах	Min	Max	
A	1.35	1.75	0.053	0.069	
A <sub>1</sub>	0.10	0.20	0.004	0.008	
В	0.35	0.51	0.014	0.020	
С	0.19	0.25	0.0075	0.010	
D	4.80	5.00	0.189	0.196	
E	3.80	4.00	0.150	0.157	
е	1.27	BSC	0.050 BSC		
Н	5.80	6.20	0.228	0.244	
h	0.25	0.50	0.010	0.020	
L	0.50	0.93	0.020	0.037	
q	0°	8°	0°	8°	
S	0.44	0.64	0.018	0.026	
ECN: C-06527-Rev. I, 11-Sep-06 DWG: 5498					



**RECOMMENDED MINIMUM PADS FOR SO-8** 



Recommended Minimum Pads Dimensions in Inches/(mm)



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